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NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARD FABRICATION METHODS MUST COMPLY WITH:
[] QORVO PCB FABRICATION SPECIFICATIONS PCB-21-101.
A COPY OF PCB-21-101 CAN BE OBTAINED FROM QORVO UPON REQUEST.
[x] FABRICATE IN ACCORDANCE WITH IPC-6018B, per IPC-6011, CLASS 3.

2. ARTWORK FORMAT: [x] GERBER 274X*
[] GERBER X2*
*GERBER DATA SUPPLIED WITH DESIRED FINAL TRACE WIDTHS, PROCESS
COMPENSATION TRACE WIDTH ADJUSTMENTS TO BE DONE BY PCB FABRICATOR.

3. MATERIAL:
NUMBER OF LAYERS: [x] 2 LAYERS [] 4 LAYERS
METAL 1: [x] 0.5oz. [] 1.0oz. [] 1.5oz. [] 2.0oz.
CORE 1: [x] ROGERS 4003C, 0.008in. THICK
[] ROGERS 4350B, 0.020in. THICK
[] FR4, 0.010in. THICK
METAL 2: [x] 0.5oz. [] 1.0oz. [] 1.5oz. [] 2.0oz.
PREPREG 1: [] EPOXY COATED GLAS FABRIC.
METAL 3: [] 0.5oz. [] 1.0oz. [] 1.5oz. [] 2.0oz.
CORE 2: [] FR4, .020in. THICK
METAL 4: [] 0.5oz. [] 1.0oz. [] 1.5oz. [] 2.0oz.
SOLDERMASK TOP: [x] LPI (LIQUID PHOTO-IMAGEABLE), [x] GREEN [] BLACK [] BLUE,
OR LD(LASED DIRECT IMAGEABLE), [x] GREEN [] BLACK [] BLUE,
MAX FINISH THICKNESS OF SOLDERMASK TO BE 0.001in.
SILKSCREEN TOP: HIGH TEMPERATURE, NON-CONDUCTIVE, WHITE EPOXY BASED INK.

4. FINISH PLATING:
METAL 1 AND METAL 2:
[x] ENIG (ELECTROLESS NICKEL/IMMERSION GOLD):
NICKEL PLATE per QQ-N-290, CLASS 1, GRADE G, 200µin. (5µm) MIN.
GOLD PLATE per ASTM B 488, TYPE III, CODE A, 3-10µin. (0.08-0.25µm)
[] IMMERSION SILVER per IPC-4553A, (6-18µin.)
[] HASL (HOT AIR SOLDER LEVEL)
[] OSP (ORGANIC SOLDER PERSERVITIVE)
METAL 1 SELECTIVE GOLD PLATING:
PLATING MUST BE FREE FROM CONTAMINATION, STAINS AND DEBRIS.
[] GOLD PLATE per ASTM B 488, TYPE III, CODE A, CLASS 1, 50µin. (1.27µm)

5. FINISHED BOARD THICKNESS: 0.011 ±0.003in.

6. COPPER IS PULLED BACK 0.002in. FROM EDGE OF BOARD ON METAL 1 AND METAL 2.
AND PULLED BACK 0.003-0.005in. FROM EDGE OF BOARD ON INTERNAL LAYERS.
THESE VALUES ARE CRITICAL AND MUST BE INSPECTED.

7. TOLERANCE: PC BOARD OUTLINE: ±0.002in.

8. BURRS SHALL NOT EXCEED 0.002in.

9. VIA PLATING/FILLING:
A. ALL VIAS UNDER THE DUT ARE TO BE:
[x] COPPER-FILLED, OVER-PLATED AND PLANARIZED,
FINISHED COPPER THICKNESS TO BE 0.0014 ±0.0004in.
[] EPOXY-FILLED, (CB100) CONDUCTIVE EPOXY, PLANARIZED.
[] EPOXY-FILLED, SAN-EI KAGAKU PHP-900 NON-CONDUCTIVE EPOXY, PLANARIZED.
B. ALL OTHER PLATED THRU HOLES TO BE PLATED TO 0.0007in. MIN. THICKNESS.
C. VIA TYPES AND LAYER ASSOCIATION USED ON BOARD:
[x] THRU-HOLE VIAS: LAYER: 1-2
[] BLIND VIAS: LAYER: X-X, X-X
[] BURIED VIAS: LAYER: X-X, X-X

10. METAL 1 TOP AND METAL2 BOTTOM SHALL BE PLANARIZED AFTER PLATING HOLES SHUT.
MAX ALLOWABLE NEGATIVE FEATURE 0.0008in. MAX ALLOWABLE POSITIVE FEATURE 0.0003in.

11. CONDUCTOR WIDTHS AND SPACING TO BE WITHIN 0.001in. OF CAD DATABASE.

12. SOLDERMASK IN PLATED-THRU HOLES IS ACCEPTABLE AS LONG AS IT DOES NOT EXIST
ON BACKSIDE OF BOARD.

13. ALL HOLES TO BE LOCATED WITHIN ±0.003 OF CAD DATABASE.

14. NO VENDOR MARKING OR SERIALIZATION ALLOWED.

15. DELIVER BOARDS BAGGED AS: [x] SINGLES
[] PANEL/ARRAY

16. 100% ELECTRICAL TEST: [] GERBER EXTRACTED NETLIST
[] IPC-D-385 FORMAT
[x] NO ELECTRICAL TEST

17. STENCIL REQUIRMENTS:
SOLDER PASTE APPLICATION MACHINE: APS (SPR-20)
TOLERANCE TO BE ±0.001in.
SPACING OF CELLS TO BE 1.00in. APART.
MATERIAL: STAINLESS STEEL, 0.005in. THICK
MARK PART: TGA2307-SM (OVM), PCB

REVISION HISTORY

ECN	REV	DESCRIPTION	DATE	APPROVAL
ECN-0001321	A	INITIAL RELEASE	7-31-2015	OMARRUFO

Metal1_Top

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UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES [mm]		PRODUCT: TGA2307-SM	
TOLERANCES ARE:		PROJECT: P-0001004	
DECIMALS .XX ± .01	METRIC [.XX ± 0.3mm]	APPROVAL AND RELEASE RECORDS MAINTAINED IN PDM	
.XXX ± .005	[.XX ± 0.13mm]	DESIGNER	DATE
.XXXX ± .0010	[.XXX ± .025mm]	OMARRUFO	05-26-15
ANGLES = ±0.5°		ENGR.	BKIM
INTERPRET DRAWING PER ANSI Y14.5-2009		MFG.	05-26-15
		MANAGER	PDM CONTROLLED
		C.A.	
THIRD ANGLE PROJECTION DO NOT SCALE DRAWING		CAGE CODE	1CVM1

SIZE		DWG. NO.	REV.
B		AD1_1127938	A
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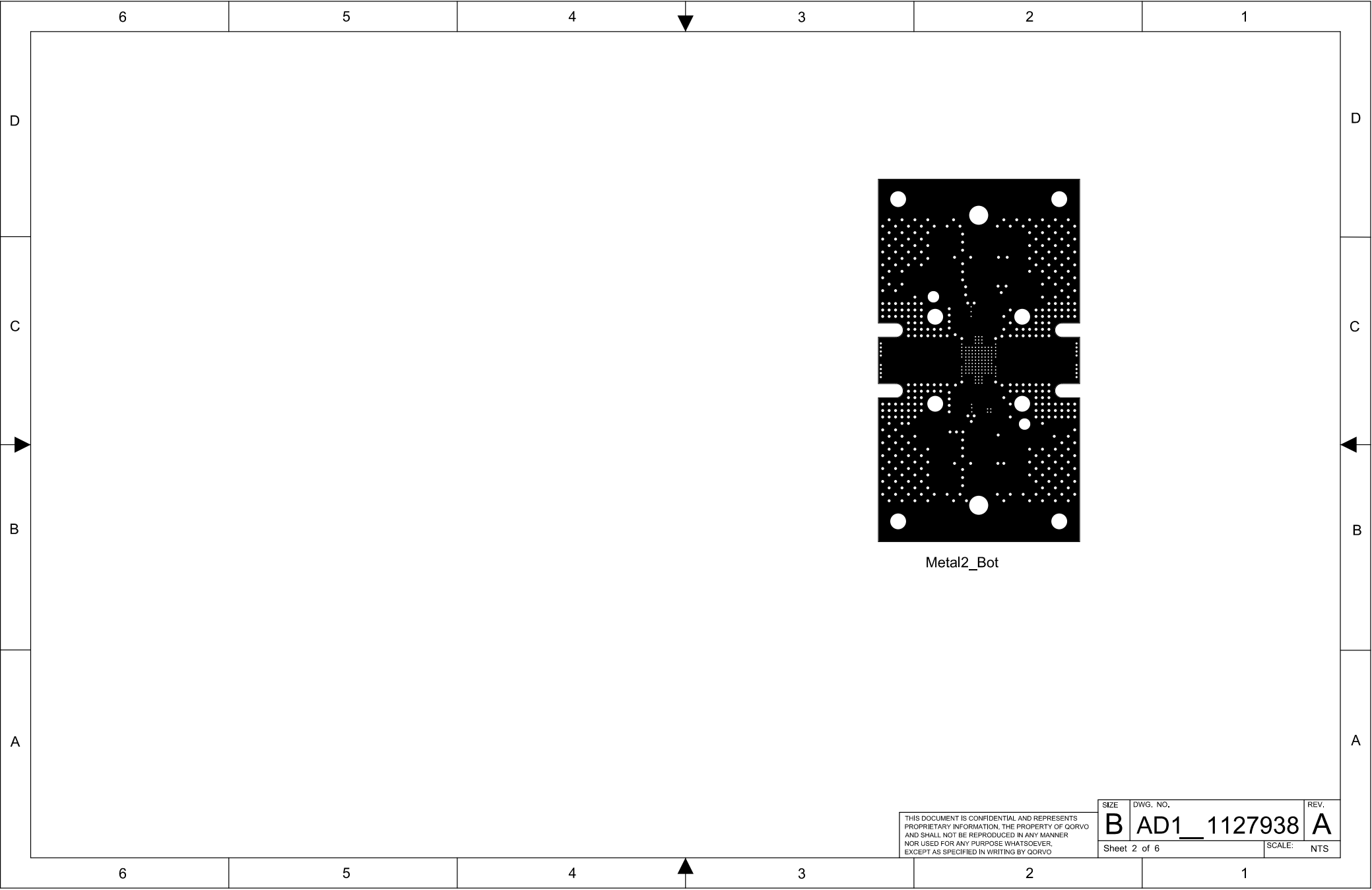
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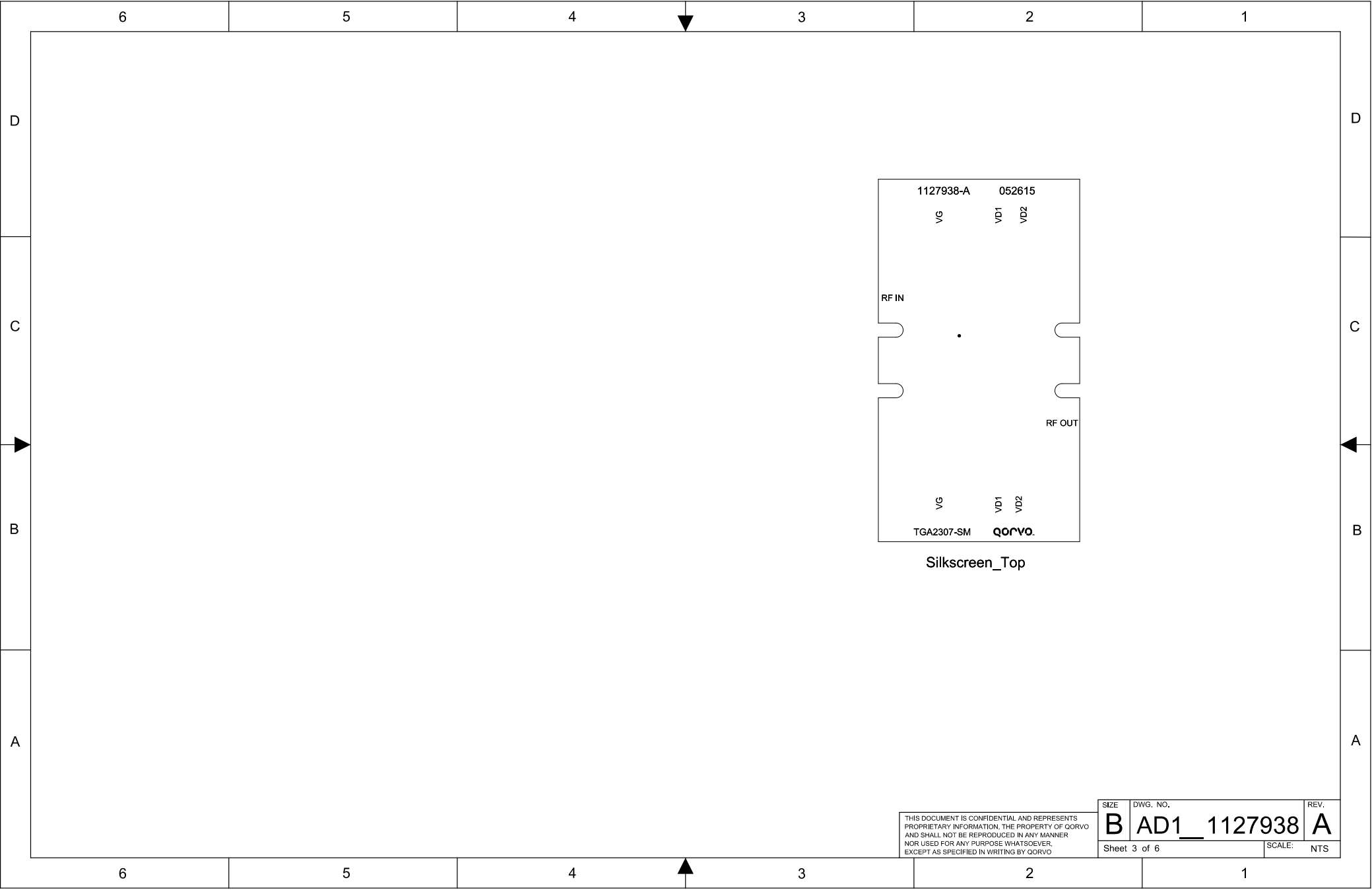
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Metal2_Bot

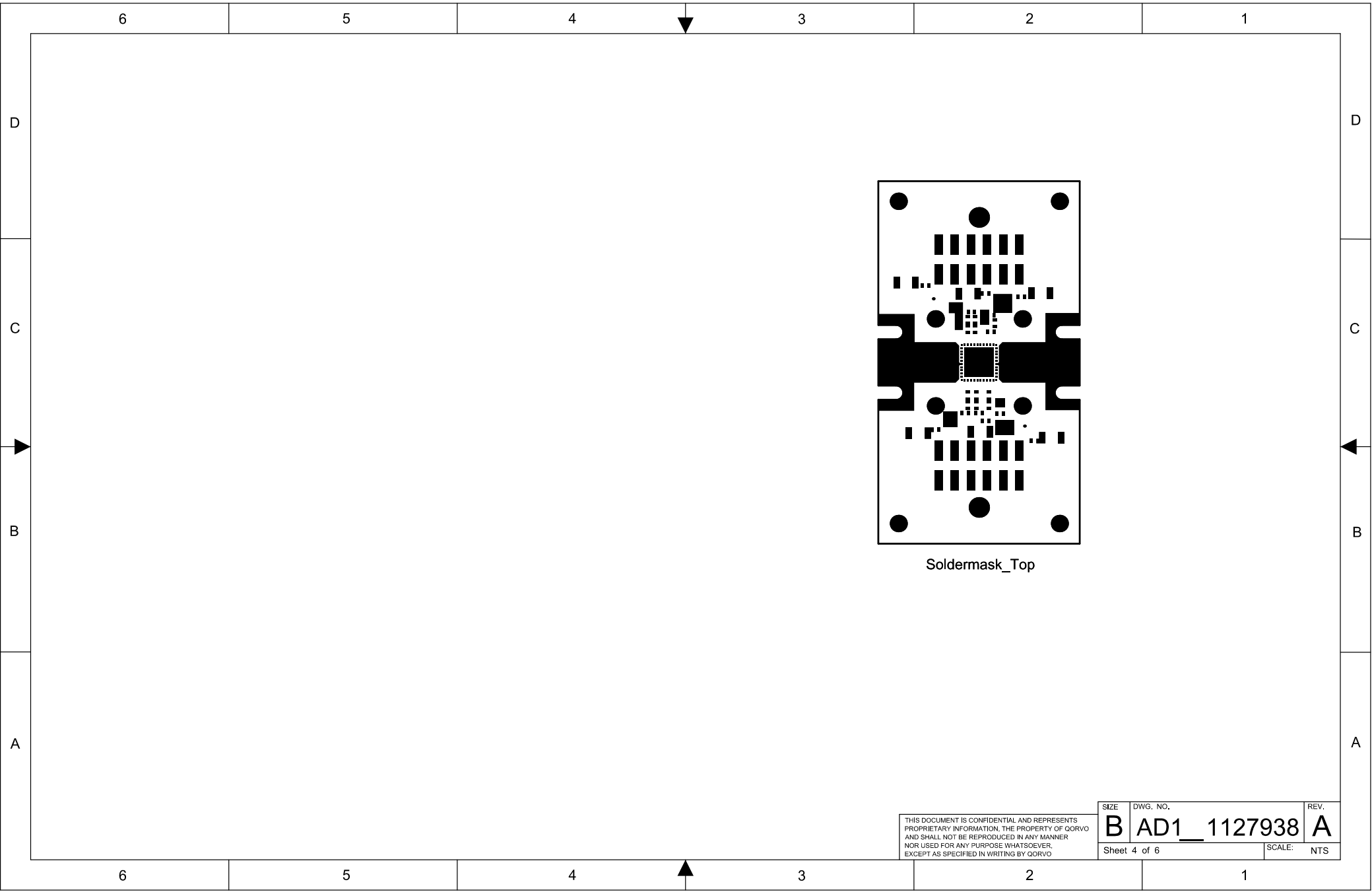
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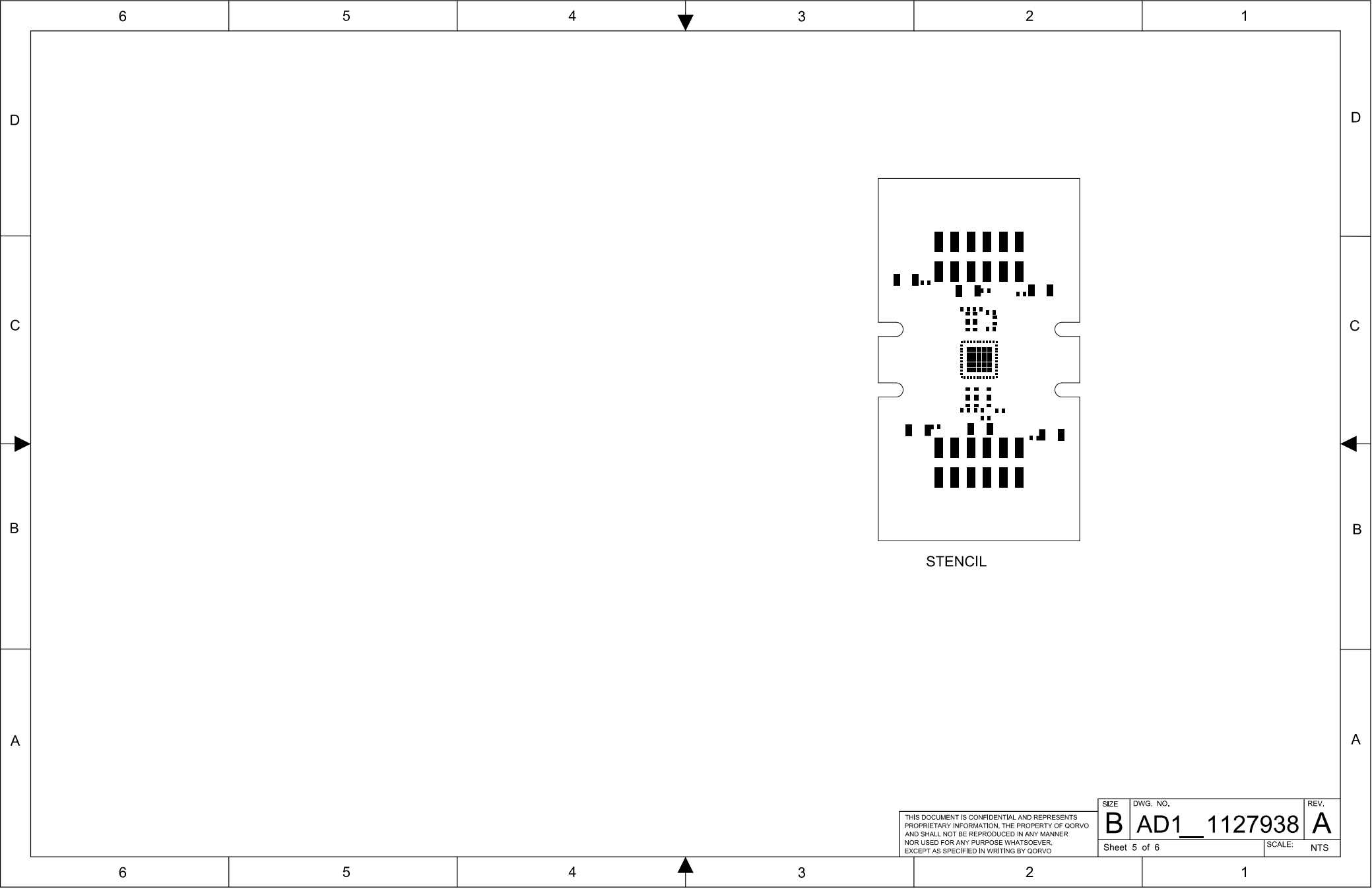
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Soldermask_Top

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Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Silkscreen_Top				
2	Soldermask_Top	Solder Resist	0.40mil	0	
3	Metal1_Top	Copper	0.70mil		
4	Dielectric 1	Rogers 4003C	8.00mil	3.38	
5	Metal2_Bot	Copper	0.70mil		

LAYER STACKUP

Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
A	127	10.00mil (0.254mm)	PTH	Round
B	16	15.00mil (0.381mm)	PTH	Round
C	396	20.00mil (0.508mm)	PTH	Round
D	2	63.00mil (1.600mm)	NPTH	Round
E	8	100.00mil (2.540mm)	PTH	Round
F	2	120.00mil (3.048mm)	PTH	Round
	551 Total			

DRILL CHART

